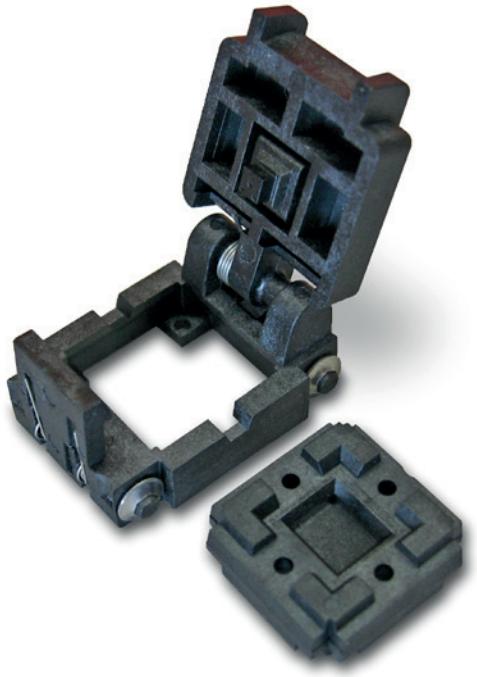
QH-Series H-Pin Socket

Accelerated life testing solution



Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

The QH-Series socket is available for all available QFN products on the market. Designed to meet the rigours of accelerated life testing applications with socket 40 part numbers available. The QH-Series is a fully moulded socket body and lid to meet the wide variety of burn-in test applications.

This socket also uses the H-Pin contact technology providing wide RF performance capabilities and exceptional DC characteristics. The QH-Series socket checks all the boxes: high frequency, high current, high temperature, low inductance, and low loss. These features result in lowering the cost of test.

Benefits

- Industry proven design, in-house tooling, moulding and machining, with 100% automated assembly.
- Extensive catalogue of components and configurable options
- H-Pin offers unmatched DC performance.

Feature Options

- Small socket footprint
- HAST venting features
- Reverse seating plane
- Max component clearance under the DUT
- 2 or 3 plate systems
- High temperature materials for above 200 °C applications

QH-Series socket specifications

Mechanical Properties:

- **Pitch**: ≥0.35 mm
- **Package Size**:
  QFN: 2 mm to 12 mm
- **Pin count**: 200
- **Temperature**: −55 °C to 260 °C

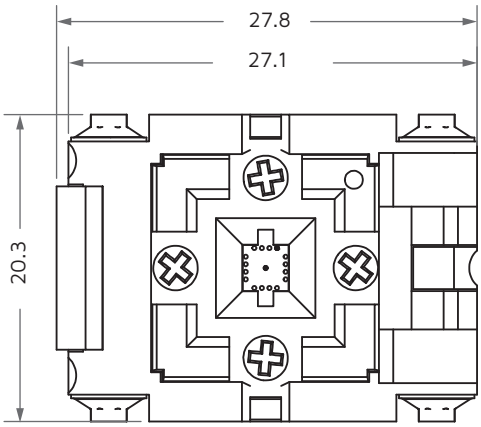
Electrical Properties

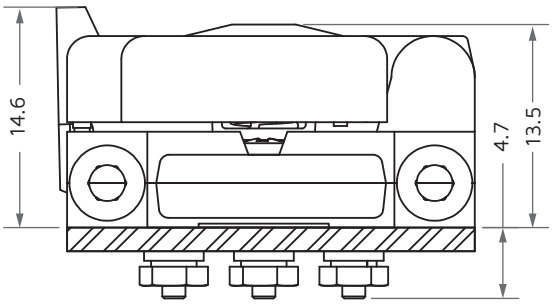
- **Contact Resistance**: 35 mΩ
- **Current Carrying Capacity**: up to 2.9 A

Materials

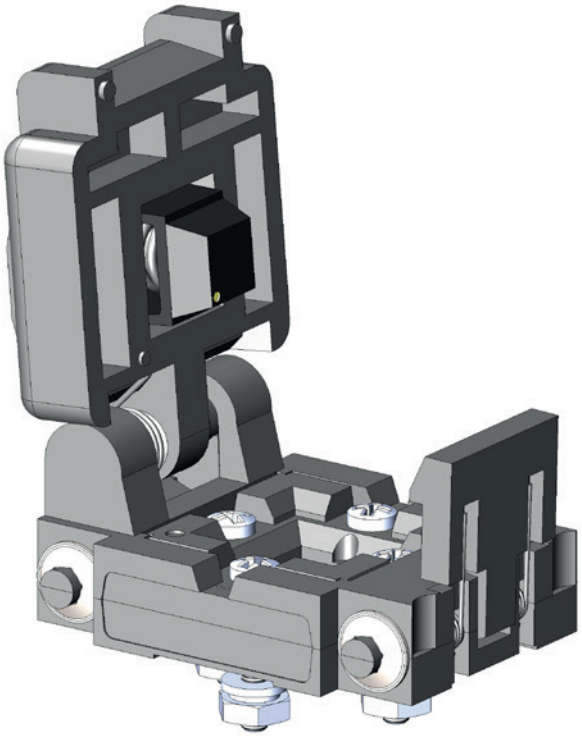
- **Contact**: BeCu/Au plated
- **Spring**: SS/Au plated
- **Socket**: Engineering plastics

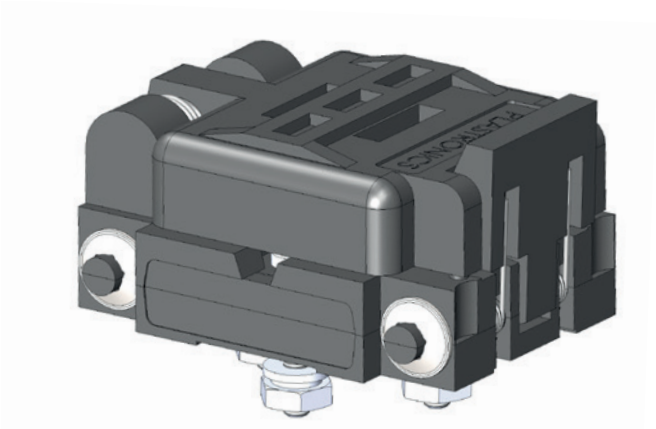
QH-Series socket dimensions





Dimensions are in mm.





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